



Patent  
Attorney's Docket No. 018976-181  
#17/1/16/04

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application of )

Akio KATSUBE et al. )

Group Art Unit: 3726 )

Application No.: 09/689,774 )

Examiner: Eric B. Compton )

Filed: October 13, 2000 )

Confirmation No.: 8104 )

For: HOLDING JIG FOR ELECTRONIC )  
PARTS, HOLDING METHOD )  
THEREFOR, AND MANUFACTURING )  
METHOD FOR ELECTRONIC PARTS )

**THIRD**  
**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Date: December 23, 2003

Sir:

In accordance with the duty of disclosure as set forth in 37 C.F.R. § 1.56, Applicants hereby submit the following information as cited in a Japanese Examination Report from a corresponding Japanese application in conformance with 37 C.F.R. §§ 1.97 and 1.98.

Pursuant to 37 C.F.R. § 1.98, a copy of each of the documents cited is enclosed.

1. JP 7-283599

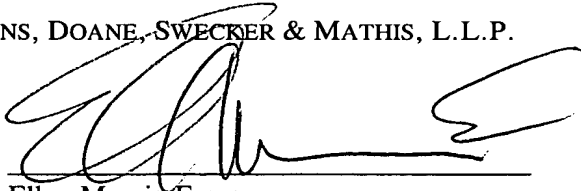
The information is submitted before the mailing of a first Office Action after the filing of a Request for Continued Examination under 37 C.F.R. § 1.114. Continued examination is requested and the fee required under 37 C.F.R. § 1.17(e) accompanies the present submission.

To assist the Examiner, the document is listed on the attached form PTO-1449. It is respectfully requested that an Examiner-initialed copy of this form be returned to the undersigned.

Respectfully submitted,

BURNS, DOANE, SWECKER & MATHIS, L.L.P.

Date: December 23, 2003

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[handwriting: illegible]

10273

Murata

Processing code: 990292 Issuance code: 418662 Date issued: Dec. 2, 2003 1

## REJECTION NOTICE

[Stamp: Dec. 2, 2003]

Patent application no.: Heisei 11 [1999]-291575  
 Date prepared: November 25, 2003  
 Patent examiner: Eiichi TANAKA 9539 4R00  
 Applicant's agent: Mr. Hisao KOBAYASHI  
 Applicable statute: Article 29, paragraphs 1 and 2

The present application is being rejected for the reasons given below. Should you object, please submit a written response within 60 days of the date of issuance of this notice.

## Reasons

1. Since the invention of the claims of the present application stated below are described in publications, stated below, that were distributed in Japan or abroad prior to filing of the present application, pursuant to the Patent Law, Article 29, paragraph 1, subparagraph 3, no patent shall issue.

2. Since, prior to filing of the present application, a person of ordinary skill in the field of art to which the invention relates could have easily arrived at the invention described in the claims of the present application stated below based on inventions described in publications which were distributed in Japan or abroad prior to filing of the present application, pursuant to the Patent Law, Article 29, paragraph 2, no patent shall issue.

Record (for references, see Table of References)

&lt; Regarding Reasons 1 and 2 &gt;

Claims 1-4, 6-7

Reference 1

Remarks

Reference 1 describes a method of manufacturing a wire-bonded semiconductor device in which a printed substrate is placed on a work table on which is provided a silicon [sic] rubber layer that stops the work from sliding.

As of the present, no reason for rejecting inventions relating to claims other than the claims indicated in this Rejection Notice have been discovered. If some new reason for rejection is discovered, notification of the reason for rejection will be provided.

Table of References

Processing code: 990292      Issuance code: 418662      Date issued: Dec. 2, 2003    2/E

1. Patent Application Publication No. Hei 7 [1995]-283599

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Record of Results of Prior Art Search

Field(s) searched: IPC, 7<sup>th</sup> Edition,    H01L 21/60

Prior art document: Patent Application Publication No. Hei 8 [1996]-186145

This Record of Results of Prior Art Search does not constitute grounds for rejection.

For inquiries relating to the contents of this Rejection Notice, contact:

Examiner Eiichi TANAKI, Electronic Materials Processing, Division 3, Patent  
Examination

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